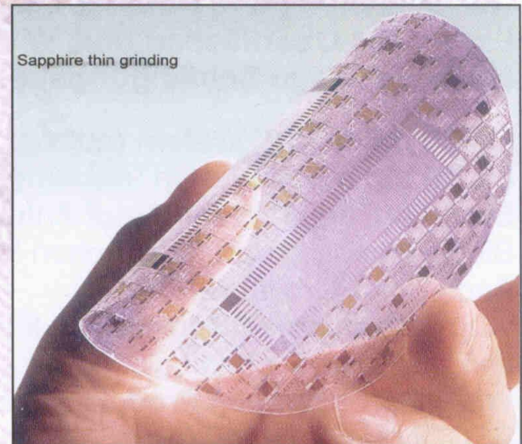
Ultrathin and thin Silicon Wafers

Ultraprecise Thinning to Target Thickness: > 30 µm

Advantages / Our Offer

- **Grinding only (no polishing), dry etching (destressed)**
- **Excellent surfaces and TTV**
- **Extremly small damage depths**



- To 70 µm at 12" wafers (also thinner on request)
- To 60 µm at 8" wafers (also thinner on request)
- To 50 µm at 6" wafers (also thinner on request)
- Single handling of ultrathin wafers
- Also solar orbital wafers
- We work on machines with advanced world standard and highest technology level
- We have experienced production managers
- SECON highspeed dry etching

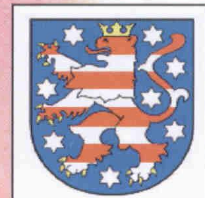
Applications

We grind on G&N NANOgrinder

Our products are mainly used for

- **SOI - preparation**
- **SOI thinning: 8" to 15 µm ultra precise**
- **MEMS**
- **RFID**
- **Stacked Wafers**
- **Bumped Wafers**
- **Bonded Wafers**

This project is part-financed by the
Europeen Union (EFRE)
and the
Free State of Thuringia (TMWTA).



my-Chip Production GmbH, Prof.-Hermann-Klare-Str. 6, D - 07407 Rudolstadt, Germany
Tel: +49 (0) 36 72 / 47 82 60, Fax:+49 (0) 36 72 / 47 82 65, , www.german-my-chip.com

Ultrathin Wafers/Chips - Diamond-Multi-Micro-Wire-Saw
Sales of Machines and Clusters - Development of Technologies - Job-Shop
Silicon, Sapphire, Glass, Quartz, Magnets, Other Brittle Crystals and Materials